

TECHNIQUES FOR MOUNTING AN AREA ARRAY PACKAGE TO
A CIRCUIT BOARD USING AN IMPROVED PAD LAYOUT

ABSTRACT OF THE DISCLOSURE

5 A circuit board assembly includes a printed circuit board (PCB). The PCB has a
pad layout which includes a set of pads arranged in a two-dimensional array having at
least two pads in a first direction and at least two pads in a second direction that is
substantially perpendicular to the first direction. Each pad has (i) a central portion and
(ii) multiple lobe portions integrated with the central portion and extending from the
10 central portion of that pad. The circuit board assembly further includes a circuit board
component mounted to the pad layout via a set of solder joints. The above-described
pad layout (or land pattern) is well-suited for soldering to a variety of AAP devices
(e.g., either a CCGA device or a BGA device).